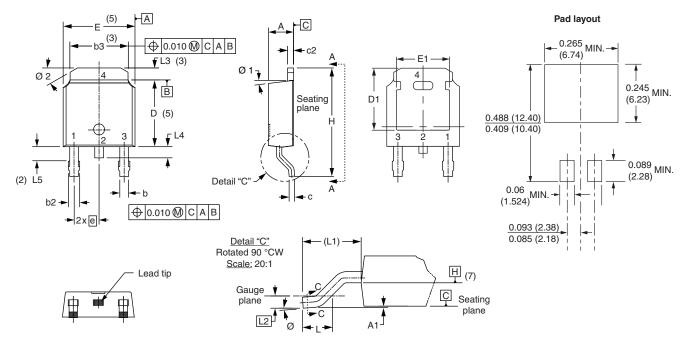


Vishay Semiconductors

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MII
	MIN.	MAX.	MIN.	MAX.	NOTES	STWBOL	MII
Α	2.18	2.39	0.086	0.094		е	:
A1	-	0.13	-	0.005		Н	9.4
b	0.64	0.89	0.025	0.035		L	1.4
b2	0.76	1.14	0.030	0.045		L1	:
b3	4.95	5.46	0.195	0.215	3	L2	(
С	0.46	0.61	0.018	0.024		L3	0.8
c2	0.46	0.89	0.018	0.035		L4	-
D	5.97	6.22	0.235	0.245	5	L5	1.1
D1	5.21	-	0.205	-	3	Ø	0°
E	6.35	6.73	0.250	0.265	5	Ø1	0°
E1	4.32	-	0.170	-	3	Ø2	25

SYMBOL	MILLIN	IETERS	INC	NOTES		
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
е	2.29 BSC		0.090			
Н	9.40	10.41	0.370	0.410		
L	1.40	1.78	0.055	0.070		
L1	2.74 BSC		0.108 REF.			
L2	0.51 BSC		0.020			
L3	0.89	1.27	0.035	0.050	3	
L4	ı	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060	2	
Ø	0°	10°	0°	10°		
Ø1	0°	15°	0°	15°		
Ø2	25°	35°	25°	35°		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA